

CLAIMS

1. A sealing resin sheet for a substrate having an electronic component built therein within a range in a thickness direction of the substrate,

the sealing resin sheet having a single layer structure having a thickness of 150 μm or more and 1000 μm or less,

the sealing resin sheet having a linear expansion coefficient of 10 ppm/K or more and 28 ppm/K or less after a heat treatment at 150°C for 1 hour.

2. The sealing resin sheet for a substrate having an electronic component built therein according to claim 1, the sealing resin sheet comprises an inorganic filler having an average particle diameter of 0.5 μm to 5 μm , wherein a content of the inorganic filler is 70 to 87% by weight.

3. The sealing resin sheet for a substrate having an electronic component built therein according to claim 1 or 2, wherein the sealing resin sheet has a minimum melt viscosity of 1 Pa•s or more and 200 Pa•s or less in a temperature range of 50°C to 200°C.

4. The sealing resin sheet for a substrate having an electronic component built therein according to any one of

claims 1 to 3, wherein the sealing resin sheet is formed by kneading extrusion.

5 5. A method for manufacturing a substrate having an electronic component built therein, the method comprising the steps of:

disposing at least one electronic component in an opening portion formed in a substrate;

10 disposing the sealing resin sheet for a substrate having an electronic component built therein according to any one of claims 1 to 4 on a substrate so as to cover the opening portion;

15 heating and pressing the sealing resin sheet for a substrate having an electronic component built therein from an upper surface side of the sealing resin sheet, to fill the opening portion of the substrate with the sealing resin sheet; and

thermally curing the sealing resin sheet for a substrate having an electronic component built therein.

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